

ABSTRACT OF THE DISCLOSURE

Provided are a high melting point copolymer prepared by heat-polymerizing cyclopentadiene and/or dicyclopentadiene and a vinyl-substituted aromatic compound, wherein a use amount of a solvent in heat polymerization is 0.1 time or more and less than 0.5 time based on the mass of the whole monomers, and the copolymer has a softening point falling in a range of 100 to 135°C, and a hydrogenated copolymer obtained by hydrogenating the above high melting point copolymer. The hydrogenated copolymer of the present invention is suitably used as an adhesion-providing resin having a high softening point for a hot melt adhesive.